MA3SE020G

Silicon epitaxial planar type

For cellular phone

■ Features

- High-frequency wave detection is possible
- Low forward voltage V_F
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	20	V
Maximum peak reverse voltage		V_{RM}	20	V
Forward current	Single	I_F	35	mA
	Series		25	
Peak forward	Single	I_{FM}	100	mA
current	Series		70	
Junction temperature		T _j	125	°C
Storage temperature		T_{stg}	-55 to +125	°C

Package

- Code SSMini3-F3
- Pin Name
 - 1: Anode 1
- 2: Cathode 2
- 3: Cathode 1 Anode 2
- Marking Symbol: M6B
- Internal Connection

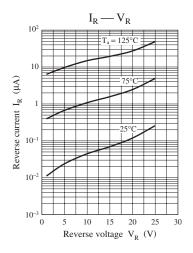


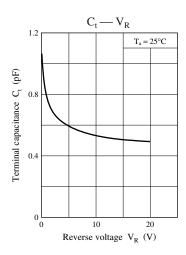
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

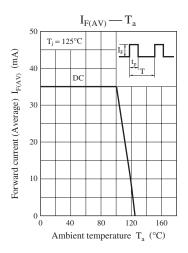
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.40	V
	V_{F2}	$I_F = 35 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 15 \text{ V}$			200	nA
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$			1.2	pF
Forward dynamic resistance	r_{f}	$I_F = 5 \text{ mA}$		9		Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

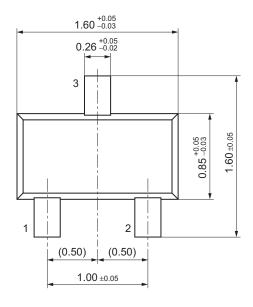
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz

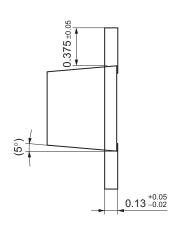


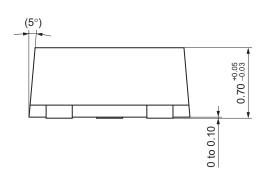


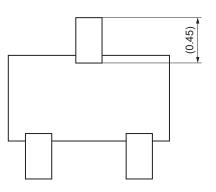


SSMini3-F3 Unit: mm









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